

Certificate of non-use of The Controlled Substances

Company name Littelfuse, Inc.

Product Covered SIDACtor®, DO-214AA & COMPAK® Package

SIDAC, DO-214AA Package

SiBOD™, DO-214AA Package, SMTBJ series

Thyristor, COMPAK[®] Package BATTRAX[®], COMPAK[®] Package

PLED, DO-214AA Package

Issue Date August 13, 2011

It is hereby certified by Littelfuse, Inc., that there is neither RoHS (EU Directive 2011/65/EU)-restricted substance, nor such use, for materials to be used for unit parts, for packing/packaging materials, and for additives and the like in the manufacturing processes.

It is also certified by Littelfuse, Inc., that the products listed in this report do not contain Halogens and their compounds judged per widely accepted industrial guidelines.

In addition, it is hereby reported to you that the parts and sub-materials, the materials to be used for unit parts, the packing/packaging materials, and the additives and the like in the manufacturing processes, are all composed of the following components.

| issued by | | | |
|-----------|--|--|--|
| | | | |
| | | | |

< K. Yoshimoto, Senior Product Engineer, Littelfuse, Inc.>

(1) Parts, sub-materials and unit parts

This document covers DO-214AA package & COMPAK package, RoHS-Compliant and Halogen-free series manufactured by Littelfuse Concord Wuxi Plant (Wuxi, China), supplied by Littelfuse, Inc. Please see page 2-5 for the complete list of part number covered by this report.

< Homogeneous Materials used>

Please see figure and table 1 on page 6 and table 2 on page 7-10 of this document.

(2) The analytical data on all measurable substances

Please see annex 1 through 7, attached to this document.

Remarks:

Pb (lead) contained in die bonding solder (item 8 on page 6) and passivation glass (item 7) to be categorized as exempt in RoHS Annex III 7(a) and 7(c)-I.

Please refer to Annex 8 of this report for the extract of the applicable exemptions of RoHS (EU Directive 2011/65/EU)

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Littelfuse Part Number covered by this report (1/3) SIDACtor® Standard Devices

| P0080SALRP | P0722SALRP | P1302SCLRP | P2302SCLRP |
|--------------|--------------|--------------|--------------|
| P0080SAMCLRP | P0722SBLRP | P1402SALRP | P2500SALRP |
| P0080SBLRP | P0722SCLRP | P1402SBLRP | P2500SBLRP |
| P0080SBMCLRP | P0900SALRP | P1500SALRP | P2500SCLRP |
| P0080SCLRP | P0900SBLRP | P1500SBLRP | P2500SCMCLRP |
| P0080SCMCLRP | P0900SCLRP | P1500SCLRP | P2600SALRP |
| P0080SDLRP | P0900SCMCLRP | P1500SCMCLRP | P2600SBLRP |
| P0220SALRP | P0900SDLRP | P1500SDLRP | P2600SCLRP |
| P0220SAMCLRP | P0901CA2LRP | P1502SALRP | P2600SCMCLRP |
| P0220SBLRP | P0901SALRP | P1502SBLRP | P2600SDLRP |
| P0220SBMCLRP | P0901SBLRP | P1502SCLRP | P2600STLRP |
| P0220SCLRP | P0901SCLRP | P1701CA2LRP | P2602SALRP |
| P0220SCMCLRP | P0902SALRP | P1701SALRP | P2602SBLRP |
| P0300SALRP | P0902SBLRP | P1701SBLRP | P2602SCLRP |
| P0300SAMCLRP | P0902SCLRP | P1701SCLRP | P3002SALRP |
| P0300SBLRP | P1100SALRP | P1800SALRP | P3002SBLRP |
| P0300SBMCLRP | P1100SBLRP | P1800SBLRP | P3002SCLRP |
| P0300SCLRP | P1100SCLRP | P1800SCLRP | P3100SALRP |
| P0300SCMCLRP | P1100SCMCLRP | P1800SCMCLRP | P3100SBLRP |
| P0640SALRP | P1100SDLRP | P1800SDLRP | P3100SCLRP |
| P0640SBLRP | P1101CA2LRP | P1800STLRP | P3100SCMCLRP |
| P0640SCLRP | P1101SALRP | P1802SALRP | P3100SDLRP |
| P0640SCMCLRP | P1101SBLRP | P1802SBLRP | P3100STLRP |
| P0640SDLRP | P1101SCLRP | P1802SCLRP | P3100SXLRP |
| P0641CA2LRP | P1102SALRP | P2000SALRP | P3500SALRP |
| P0641SALRP | P1102SBLRP | P2000SBLRP | P3500SBLRP |
| P0641SBLRP | P1102SCLRP | P2000SCLRP | P3500SCLRP |
| P0641SCLRP | P1200SALRP | P2000SCMCLRP | P3500SCMCLRP |
| P0642SALRP | P1200SBLRP | P2100SALRP | P3500SDLRP |
| P0642SBLRP | P1200SCLRP | P2100SBLRP | P3500STLRP |
| P0642SCLRP | P1200SCMCLRP | P2100SCLRP | P3502SALRP |
| P0720SALRP | P1300SALRP | P2100SCMCLRP | P3502SBLRP |
| P0720SBLRP | P1300SBLRP | P2300SALRP | P3502SCLRP |
| P0720SCLRP | P1300SCLRP | P2300SBLRP | P3502SCLRP |
| P0720SCMCLRP | P1300SCMCLRP | P2300SCLRP | P4202SALRP |
| P0720SDLRP | P1300SDLRP | P2300SCMCLRP | P4202SCLRP |
| P0721CA2LRP | P1301CA2LRP | P2300SDLRP | P4802SALRP |
| P0721SALRP | P1301SCLRP | P2300STLRP | P4802SCLRP |
| P0721SBLRP | P1302SALRP | P2302SALRP | P6002SALRP |
| P0721SCLRP | P1302SBLRP | P2302SBLRP | P6002SCLRP |
| | | | P7002SCLRP |

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Littelfuse Part Number covered by this report (2/3) SIDACtor® Special Devices

| | | · · · · · · · · · · · · · · · · · · · |
|-----------------|---------|-----------------------------------------------------------------|
| P376P1500SCRP | P923CRP | |
| P486P3100SBRP | P923WRP | Special device part numbers with base part |
| P618P3100SCRP | P925CRP | number listed in table 1/3 (standard devices) |
| P640P3100SBRP | P925WRP | are also automatically covered. |
| P641P3100SCRP | P926CRP | |
| P651P3100SARP | P926WRP | Their typical part number format is |
| P653P2600SBRP | P927CRP | PxxxPxxxxSxLRP. |
| P654P3100SBRP | P927WRP | "L" at 3 rd digit from right denotes RoHS-compliant. |
| P654P3100SBRPH | P931CRP | 7 |
| P654P3100SBRPHF | P931WRP | |
| P655P3500SBRP | | |
| P658P0300SARP | | |
| P659P0640SARP | | |
| P674P1500SCRP | | |
| P675P1100SARP | | |
| P676P0640SCRP | | |
| P677P1800SCRP | | |
| P678P0080SBRP | | |
| P686P2300SBRP | | |
| P688P1100SARP | | |
| P689P1100SCRP | | |
| P691P0300SCMCRP | | |
| P692P3500SDRP | | |
| P695P0300SARP | | |
| P697P1300SARP | | |
| P698CRP | | |
| P698WRP | | |
| P707P3100SARP | | |
| P708P2300SBRP | | |
| P712P0640SARP | | |
| P716P3500SARP | | |
| P746P2600SDRP | | |
| P760ALRP | | |
| P760BLRP | | |
| P760LRP | | |
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| | 1 | |

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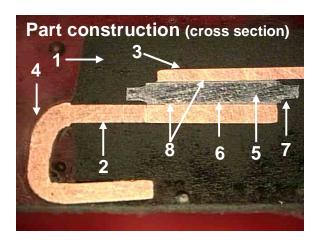
Littelfuse Part Number covered by this report (3/3) SIDAC, SiBOD™, Thyristor, BATTRAX® and PLED Devices

| SIDAC | SiBOD | | Thyristor |
|--------------|---------------|--------|------------|
| K0820SRP | SMTBJ050A | L2N3RP | S4S3RP |
| K0900SRP | SMTBJ050B | L2N5RP | S4SRP |
| K1050SRP | SMTBJ056A-006 | L2X3RP | S6N1RP |
| K1100SRP | SMTBJ070B | L2X5RP | S6S1RP |
| K1200SRP | SMTBJ100B | L4N3RP | S6S2RP |
| K1300SRP | SMTBJ108A-006 | L4N5RP | S6S3RP |
| K1400SRP | SMTBJ120A | L4N6RP | S6SRP |
| K1500SRP | SMTBJ162A-006 | L4N8RP | S813S4N1RP |
| K1800SRP | SMTBJ170A | L4X3RP | S827S4S2RP |
| K1801SRP | SMTBJ180A-006 | L4X5RP | S828S4S1RP |
| K2000SHRP | SMTBJ200A | L4X6RP | S853S4S3RP |
| K2000SRP | SMTBJ200B | L4X8RP | S856S4SRP |
| K2200SHRP | SMTBJ216A-006 | L6N3RP | S872S4S2RP |
| K2200SRP | SMTBJ240A | L6N5RP | S893S4SRP |
| K2400SHRP | | L6N6RP | |
| K2400SRP | | L6N8RP | |
| K2500SHRP | | L6X3RP | |
| K2500SRP | | L6X5RP | DATTD A V® |
| K222K1500SRP | | L6X6RP | BATTRAX® |
| K226K1500SRP | | L6X8RP | B1100CALRP |
| K240K2500SRP | | Q2N3RP | B1100CCLRP |
| K260K2500SRP | | Q2N4RP | B1160CALRP |
| K282K2500SRP | | Q2X3RP | B1160CCLRP |
| K298K1400SRP | | Q2X4RP | B1200CALRP |
| K300K1801SRP | | Q4N3RP | B1200CCLRP |
| K301K1500SRP | | Q4N4RP | B2050CCLRP |
| K303K1200SRP | | Q4X3RP | |
| K305K1500SRP | | Q4X4RP | DI ED |
| K306K1300SRP | | Q6N3RP | PLED |
| | | Q6N4RP | PLED6S |
| | | Q6X3RP | PLED9S |
| | | Q6X4RP | PLED13S |
| | | S2N1RP | PLED18S |
| | | S2S1RP | PLES6US |
| | | S2S2RP | PLED9US |
| | | S2S3RP | PLED13US |
| | | S2SRP | PLED18US |
| | | S4N1RP | |

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Expertise Applied | Answers Delivered



Material Used (where used)

This photo is for explanation only.

Actual assembly design may be different.

Table 1: Homogeneous Material Used

| # | Description | Name of Material | Туре | Analysis data |
|---|--------------------|---------------------|---------|-----------------------------------------------------------------------------------------------------------------|
| 1 | Molding compound | epoxy resin | plastic | annex 1 |
| 2 | Lead frame | copper alloy | metal | annex 2 DO-214AA package uses same raw material and same supplier as TO-220. Report is from TO-220 material. |
| 3 | Clip | copper alloy | metal | annex 3 |
| 4 | Matte-Tin plating | Tin | metal | annex 4 |
| 5 | Silicon die | silicon | metal | annex 5, tested as Nickel-plated wafer. |
| 6 | Nickel electrode | nickel | metal | alliex 5, tested as Nicker-plated water. |
| 7 | Passivation glass | glass | glass | annex 6 Pb in this glass is exempted by RoHS Annex III 7(c)-I. Please refer to Annex 8 for the RoHS exemption. |
| 8 | Die bonding solder | solder | metal | annex 7 Pb in this solder is exempted by RoHS Annex III 7(a). Please refer to Annex 8 for the RoHS exemption. |

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Table 2-1: RoHS-regulated substance in raw materials

| Components & Raw Materials | Analytical Test Result | | | | | | |
|-------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|----------------|---------------|--------------------------------------------|--------|--------|------------------|
| Componente a rew materiale | | | | | | | |
| | Cd Cadmium | Cr Chromium | Hg Mercury | Pb Lead | PBB | PBDE | TOTAL HALOGEN |
| As Component Total Values of P3100SDLRP* ¹ , as representative products of all DO-214 and COMPAK package See Annex 8 for whole component test. | < 2ppm | < 2ppm | < 2ppm | <10 ppm* ² (3.0% ³) | < 5ppm | < 5ppm | < 88ppm |
| Epoxy Resin compound | | | | | | | |
| See Annex 1 for the detail. | < 2ppm | < 1ppm | < 2ppm | < 2ppm | < 5ppm | < 5ppm | 88ppm |
| Lead frame (Copper Alloy, KFC) See Annex 2 for the detail. | < 2ppm | < 2ppm | < 2ppm | 20ppm*4 | | | |
| Clip (Copper Alloy 110) See Annex 3 for the detail. | < 2ppm | < 2ppm | < 2ppm | < 2ppm | | | |
| Outside lead finish (Sn 100%) See Annex 4 for the detail. | < 2ppm | < 2ppm | < 2ppm | 29ppm* ⁴ | | | |
| Silicon Die (Silicon + Ni electrode) See Annex 5 for the detail. | < 2ppm | < 2ppm | < 2ppm | 48ppm* ⁴ | < 5ppm | < 5ppm | <50ppm |
| Passivation Glass See Annex 6 for the detail. | < 2ppm | < 2ppm | < 2ppm | 40% *5 | < 5ppm | < 5ppm | <50ppm |
| Die Bonding Solder (Pb/Sn=90/10) See Annex 7 for the detail. | < 2ppm | < 2ppm | < 2ppm | 90% ^{*6} | < 5ppm | < 5ppm | <50ppm |

- *1 Other products may contain equal or less amount of Pb as P3100SDLRP value shown here, but not more than the value shown here.
- *2 Less than 10ppm Pb content overall, <u>excluding</u> Pb from the die bonding solder and the passivation glass on the silicon die.
- *3 Maximum 3.0wt% or 3.0mg of Pb (lead) content overall, including the RoHS-exempted use of Pb
- *4 Pb (lead) contained in lead frame, outside plating and silicon wafer is <u>not</u> exempted from restriction by RoHS, but considered as process contamination or naturally-occurring impurity in raw materials. Littelfuse does not add Pb (lead) intentionally.
- *5 Pb (lead) contained in passivation glass is exempted from restriction by RoHS Annex III 7(c)-l.
- *6 Pb (lead) contained in die bonding solder is exempted from restriction by RoHS Annex III 7(a).

 Please refer to Annex 8 of this report for the applicable exemptions of RoHS (EU Directive 2011/65/EU)

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Annex 1: Analysis Result of Molding Compound (Page 1 of 7)



TEST REPORT Number: WUXH00005739

Applicant: CONCORD SEMICONDUCTOR(WUXI) CO., LTD. Date:

EAST 1#,ZHENFA 6 ROAD, SHUO FANG INDUSTRIAL PARK

WUXI NATIONAL HIGH-TECH DEVELOPMENT ZONE,

WUXI,JIANGSU,CHINA Attn: ZHANG XIAOPENG

Sample Description As Declared:

One (1) Piece Of Submitted Sample Said To Be: Brown Epoxy Molding Compound.

Item Name : Epoxy Molding Compound.

Vendor : Cookson Electonics Semiconductor Products.

Component Or Part No. : CK-2000A/CK-2000C.

Test Item : Cd,Pb,Hg,CrVI,PBBs,PBDEs,F,Cl,Br,I.

Tests Conducted:

As Requested By The Applicant, For Details Refer To Attached Pages

Summary:

Tested Sample

Standard

With Reference To Test Method Of IEC 62321 Edition

Submitted Sample

1.0: 2008 And Maximum Concentration Limits Quoted

PASS

PASS

From RoHS Directives 2002/95/EC And Amendment

2005/618/EC

Prepared And Checked By:

For Intertek Testing Services Wuxi Ltd.

Jessica Lu General Manager

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Aug 05, 2011

Intertek Testing Services Wuxi Ltd.



Annex 1: Analysis Result of Molding Compound (Page 2 of 7)



TEST REPORT Number: WUXH00005739

Tests Conducted (As Requested By The Applicant)

1 RoHS Directives Test

(A) Test Result Summ

| (A) Test Result Summary: | . . |
|------------------------------------------------------------------|------------|
| Testing Item | Result |
| Cadmium (Cd) Content (mg/kg) | ND |
| Lead (Pb) Content (mg/kg) | ND |
| Mercury (Hg) Content (mg/kg) | ND |
| Chromium (VI) (Cr ⁶⁺) Content (mg/kg)(For Non-Metal) | ND |
| Polybrominated Biphenyls (PBBs)(mg/kg) | |
| Monobrominated Biphenyls (MonoBB) | ND |
| Dibrominated Biphenyls (DiBB) | ND |
| Tribrominated Biphenyls (TriBB) | ND |
| Tetrabrominated Biphenyls (TetraBB) | ND |
| Pentabrominated Biphenyls (PentaBB) | ND |
| Hexabrominated Biphenyls (HexaBB) | ND |
| Heptabrominated Biphenyls (HeptaBB) | ND |
| Octabrominated Biphenyls (OctaBB) | ND |
| Nonabrominated Biphenyls (NonaBB) | ND |
| Decabrominated Biphenyl (DecaBB) | ND |
| Polybrominated Diphenyl Ethers (PBDEs)(mg/kg) | |
| Monobrominated Diphenyl Ethers (MonoBDE) | ND |
| Dibrominated Diphenyl Ethers (DiBDE) | ND |
| Tribrominated Diphenyl Ethers (TriBDE) | ND |
| Tetrabrominated Diphenyl Ethers (TetraBDE) | ND |
| Pentabrominated Diphenyl Ethers (PentaBDE) | ND |
| Hexabrominated Diphenyl Ethers (HexaBDE) | ND |
| Heptabrominated Diphenyl Ethers (HeptaBDE) | ND |
| Octabrominated Diphenyl Ethers (OctaBDE) | ND |
| Nonabrominated Diphenyl Ethers (NonaBDE) | ND |
| Decabrominated Diphenyl Ether (DecaBDE) | ND |

mg/kg = Milligram Per Kilogram = ppm ND = Not Detected

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Intertek Testing Services Wuxi Ltd.



Annex 1: Analysis Result of Molding Compound (Page 3 of 7)



TEST REPORT Number: WUXH00005739

Tests Conducted (As Requested By The Applicant)

(B)RoHS Requirement:

| (b)Norio requirement. | |
|----------------------------------------|-------------------|
| Restricted Substances | Limits |
| Cadmium (Cd) | 0.01% (100 mg/kg) |
| Lead (Pb) | 0.1% (1000 mg/kg) |
| Mercury (Hg) | 0.1% (1000 mg/kg) |
| Chromium (VI) (Cr ⁶⁺) | 0.1% (1000 mg/kg) |
| Polybrominated Biphenyls (PBBs) | 0.1% (1000 mg/kg) |
| Polybrominated Diphenyl Ethers (PBDEs) | 0.1% (1000 mg/kg) |

The Above Limits Were Quoted From 2002/95/EC And Amendment 2005/618/EC For Homogeneous Material.

(C) Test Method:

| <u>Testing Item</u> | <u>Testing Method</u> | Reporting Limit |
|-------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------|-----------------|
| Cadmium (Cd)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Lead (Pb)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Mercury (Hg)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Chromium (VI) (Cr ^{é+}) Content (For Non-Metal) | With Reference To IEC 62321 Edition 1.0: 2008, By Alkaline Digestion And Determined By UV-VIS Spectrophotometer | 1 mg/kg |
| Polybrominated Biphenyls (PBBs)& Polybrominated Diphenyl Ethers (PBDEs) | With Reference To IEC 62321 Edition 1.0: 2008, By Solvent Extraction And Determined By GC-MSD And Further HPLC Confirmation When Necessary. | 5 mg/kg |

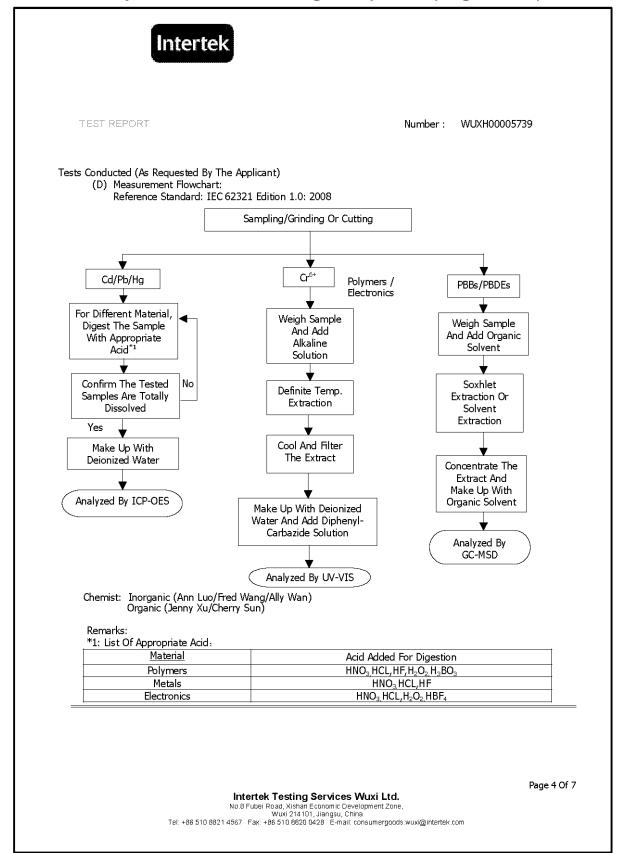
Date Sample Received: Aug 01, 2011 Testing Period: Aug 01, 2011 To Aug 05, 2011

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Intertek Testing Services Wuxi Ltd.



Annex 1: Analysis Result of Molding Compound (Page 4 of 7)



August 13, 2011 Littelfuse, Inc. Annex 1-4



Annex 1: Analysis Result of Molding Compound (Page 5 of 7)



TEST REPORT Number: WUXH00005739

Tests Conducted (As Requested By The Applicant)

Halogen Test

(I) Test Result Summary :

Halogen Content:

| Testing Item | Result (ppm) |
|----------------------|--------------|
| Fluorine (F) Content | ND |
| Chlorine (Cl)Content | 88 |
| Bromine (Br) Content | ND |
| Iodine (I) Content | ND |

Remarks: ppm = Parts Per Million = mg/kg

ND = Not Detected

Date Sample Received: Aug 01, 2011

Testing Period: Aug 01, 2011 To Aug 05, 2011

(II) Test Method:

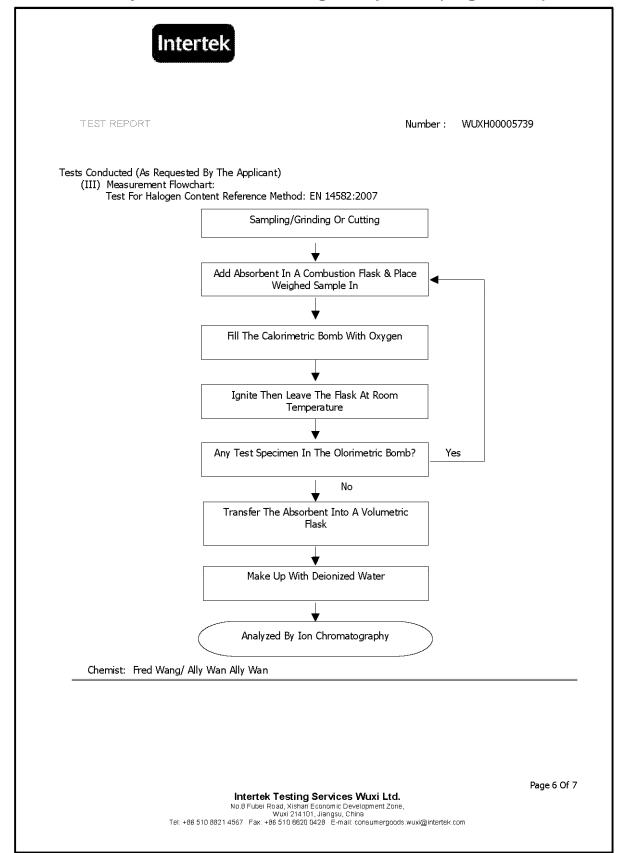
| Testing Item | Testing Method | Reporting Limit | |
|--------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------|--------------------|--|
| | With Reference EN 14582:2007 By Combustion In A Calorimetric Bomb And Determined By Ion Chromatography | 50 ppm | |
| Remarks: Reporting Limit = Quantitation Limit Of Analyte In Sample | | | |

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Intertek Testing Services Wuxi Ltd.

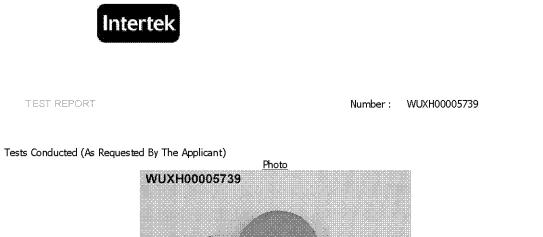


Annex 1: Analysis Result of Molding Compound (Page 6 of 7)





Annex 1: Analysis Result of Molding Compound (Page 7 of 7)



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Intertek Testing Services Wuxi Ltd.



Annex 2: Analysis Result of Lead frame (Page 1 of 4)



TEST REPORT Number: WUXH00005713

Applicant: CONCORD SEMICONDUCTOR(WUXI) CO., LTD.

Date: Aug 04, 2011 EAST 1#,ZHENFA 6 ROAD, SHUO FÁNG INDUSTRIAL PARK

WUXI NATIONAL HIGH-TECH DEVELOPMENT ZONE,

WUXI,JIANGSU,CHINA Attn: ZHANG XIAOPENG

Sample Description As Declared:

One (1) Piece Of Submitted Sample Said To Be: Golden Yellow Metal.

: Lead Frame/Lead Frame Matrix/TO-220 Lead Frame/Heatsink. Item Name

Vendor Jinag Jihlong Technology CO.,LTD.

Component Or Part No. : Copper. Test Item : Cd,Pb,Hg,CrVI.

Tests Conducted:

As Requested By The Applicant, For Details Refer To Attached Pages

Tested Sample Standard Result With Reference To Test Method Of IEC 62321 Edition Submitted Sample 1.0: 2008 And Maximum Concentration Limits Quoted PASS From RoHS Directives 2002/95/EC And Amendment

2005/618/EC

Prepared And Checked By: For Intertek Testing Services Wuxi Ltd.

Jessica Lu General Manager

Page 1 Of 4

Intertek Testing Services Wuxi Ltd.



Annex 2: Analysis Result of Lead frame (Page 2 of 4)



TEST REPORT Number: WUXH00005713

Tests Conducted (As Requested By The Applicant)

RoHS Directives Test

(A) Test Result Summary:

| (,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,, | |
|-------------------------------------------------------------------------|--------|
| Testing Item | Result |
| Cadmium (Cd) Content (mg/kg) | ND |
| Lead (Pb) Content (mg/kg) | 20 |
| Mercury (Hg) Content (mg/kg) | ND |
| Chromium (VI)(Cr ⁶⁺) Result (By Boiling Water Extraction On | N |
| Metal) (mg/kg With 50cm²) | IN |

Damark

mg/kg = Milligram Per Kilogram = ppm

mg/kg With 50cm² = Milligram Per Kilogram With 50 Square Centimeter

ND = Not Detected

N=Negative

(B)RoHS Requirement:

| Restricted Substances | Limits |
|-----------------------------------|-------------------|
| Cadmium (Cd) | 0.01% (100 mg/kg) |
| Lead (Pb) | 0.1% (1000 mg/kg) |
| Mercury (Hg) | 0.1% (1000 mg/kg) |
| Chromium (VI) (Cr ⁶⁺) | 0.1% (1000 mg/kg) |

The Above Limits Were Quoted From 2002/95/EC And Amendment 2005/618/EC For Homogeneous Material.

(C) Test Method:

| <u>Testing Item</u> | <u>Testing Method</u> | Reporting Limit |
|---------------------|-----------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------|
| Cadmium (Cd)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Lead (Pb)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Mercury (ng)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| I(For Metal) | With Reference To IEC 62321 Edition 1.0: 2008, By Boiling Water Extraction And Determined By UV-VIS Spectrophotometer | 0.02mg/kg With 50cm² (In Testing Solution) |

Date Sample Received: Aug 01, 2011

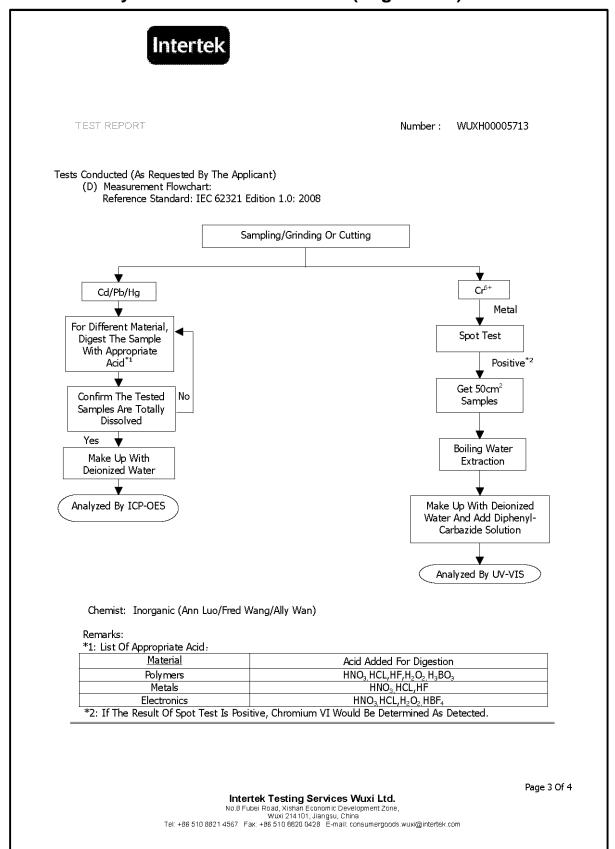
Testing Period: Aug 01, 2011 To Aug 03, 2011

Page 2 Of 4

Intertek Testing Services Wuxi Ltd.



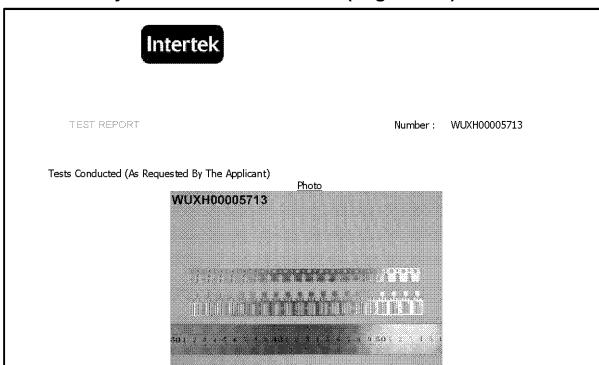
Annex 2: Analysis Result of Lead frame (Page 3 of 4)



August 13, 2011 Littelfuse, Inc. Annex 2-3



Annex 2: Analysis Result of Lead frame (Page 4 of 4)



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Intertek Testing Services Wuxi Ltd.



Annex 3: Analysis Result of Clip (Page 1 of 5)



TEST REPORT Number: WUXH00005729S1

Applicant: CONCORD SEMICONDUCTOR(WUXI) CO., LTD.

EAST 1#,ZHENFA 6 ROAD, SHUO FÁNG INDUSTRIAL PARK THIS IS TO SUPERSEDE REPORT WUXI NATIONAL HIGH-TECH DEVELOPMENT ZONE, NO. WUXH00005729 DATED

WUXI,JIANGSU,CHINA

AUG 04, 2011 Attn: ZHANG XIAOPENG

Sample Description As Declared:

One (1) Piece Of Submitted Sample Said To Be: Golden Yellow Metal.

Item Name : Clip.

Vendor : G-SHANK Precision Machinery (Suzhou)CO., LTD.

Component Or Part No. : Copper. Test Item : Cd,Pb,Hg,CrVI.

Tests Conducted:

As Requested By The Applicant, For Details Refer To Attached Pages

Summary:

Tested Sample <u>Standard</u> <u>Result</u> Submitted Sample With Reference To Test Method Of IEC 62321 Edition

1.0: 2008 And Maximum Concentration Limits Quoted From RoHS Directives 2002/95/EC And Amendment

2005/618/EC

Prepared And Checked By:

For Intertek Testing Services Wuxi Ltd.

Jessica Lu General Manager

Page 1 Of 4

Aug 12, 2011

Date:

Intertek Testing Services Wuxi Ltd.



Annex 3: Analysis Result of Clip (Page 2 of 5)



TEST REPORT Number: WUXH00005729S1

Tests Conducted (As Requested By The Applicant)

1 RoHS Directives Test

(A) Test Result Summary:

| Testing Item | Result |
|----------------------------------------------------------------------------------------------------------------|--------|
| Cadmium (Cd) Content (mg/kg) | ND |
| Lead (Pb) Content (mg/kg) | ND |
| Mercury (Hg) Content (mg/kg) | ND |
| Chromium (VI)(Cr ⁶⁺) Result (By Boiling Water Extraction On Metal) (mg/kg With 50cm ²) | N |

Remark

mg/kg = Milligram Per Kilogram = ppm

mg/kg With 50cm² = Milligram Per Kilogram With 50 Square Centimeter

ND = Not Detected

N=Negative

(B)RoHS Requirement:

| Restricted Substances | Limits |
|-----------------------------------|-------------------|
| Cadmium (Cd) | 0.01% (100 mg/kg) |
| Lead (Pb) | 0.1% (1000 mg/kg) |
| Mercury (Hg) | 0.1% (1000 mg/kg) |
| Chromium (VI) (Cr ⁶⁺) | 0.1% (1000 mg/kg) |

The Above Limits Were Quoted From 2002/95/EC And Amendment 2005/618/EC For Homogeneous Material.

(C) Test Method:

| <u>Testing Item</u> | <u>Testing Method</u> | Reporting Limit |
|----------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------|
| Cadmium (Cd)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Lead (Pb)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Mercury (Hg)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Chromium (VI) (Cr ⁶⁺) Content (For Metal) | With Reference To IEC 62321 Edition 1.0: 2008, By Boiling Water Extraction And Determined By UV-VIS Spectrophotometer | 0.02mg/kg With 50cm² (In Testing Solution) |

Date Sample Received: Aug 01, 2011

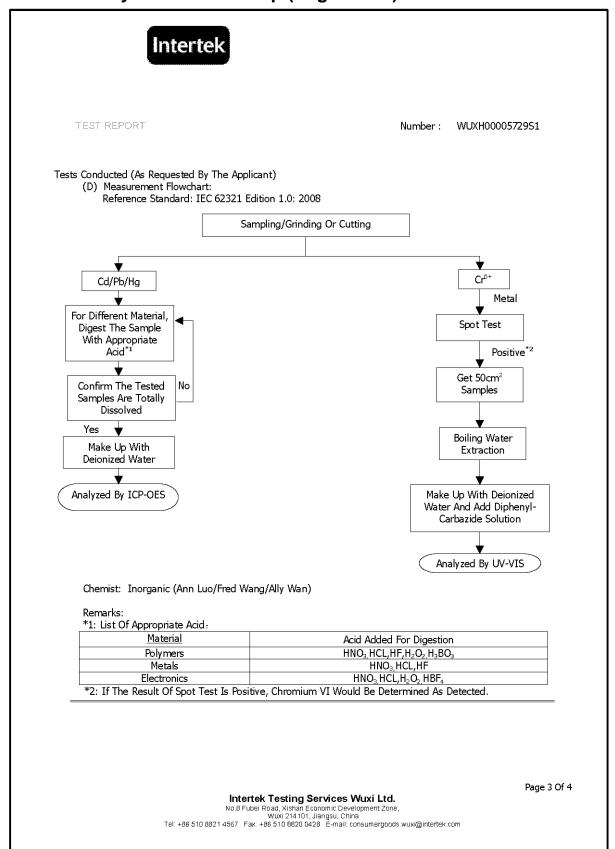
Testing Period: Aug 01, 2011 To Aug 04, 2011

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Intertek Testing Services Wuxi Ltd.



Annex 3: Analysis Result of Clip (Page 3 of 5)



August 13, 2011 Littelfuse, Inc. Annex 3-3

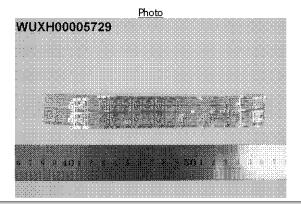


Annex 3: Analysis Result of Clip (Page 4 of 5)



TEST REPORT Number : WUXH00005729S1

Tests Conducted (As Requested By The Applicant)



Page 4 Of 4

Intertek Testing Services Wuxi Ltd.
No.8 Fubel Road, Xishan Economic Development Zone,
Wuxi 214101, Jiangsu, China
Tel: +86 510 8821 4567 Fax: +86 510 8820 6428 E-mail: consumergoods wuxi@intertek.com



Annex 3: Analysis Result of Clip (Page 5 of 5)



To : CONCORD SEMICONDUCTOR(WUXI) CO., LTD.

Attention: ZHANG XIAOPENG Date: Aug 12, 2011

Re : Report Revision Notification

Labtest Report Number WUXH00005729 date AUG 04, 2011

Please be informed that all the content recorded in the above captioned report will be void. This captioned report is now superseded by a revised Labtest Report, Number WUXH00005729S1 , issued on Aug 12, 2011 .

Thank you for your attention

Prepared And Checked By: For Intertek Testing Services Wuxi Ltd.

Jessica Lu General Manager

Intertek Testing Services Wuxi Ltd.
No.3 Fubel Pload, Xishan Economic Development Zone,
Vivud 214101, Jüngeu, China
無錫天祥實量技術服務有限公司
中國江英海绵科山政海斯曼虽治本路路,數集场,214101

Tel: +86 510 8821 4567 Fex: +86 510 8820 0428 E-mail: consumergoods.wuxi@intertek.com



Annex 4: Analysis Result of Matte-Tin plating (page 1 of 4)



TEST REPORT Number: WUXH00005709

Applicant: CONCORD SEMICONDUCTOR(WUXI) CO., LTD. Date: Aug 04, 2011

EAST 1#,ZHENFA 6 ROAD, SHUO FÁNG INDUSTRIAL PARK WUXI NATIONAL HIGH-TECH DEVELOPMENT ZONE, WUXI,JIANGSU,CHINA

Attn: ZHANG XIAOPENG

Sample Description As Declared:

One (1) Piece Of Submitted Sample Said To Be: Black Plastic With Silvery Metal Pin.

Item Name : Tin Plating-SMD.

Vendor : Bandl (Kunshan) International Co.,.

Component Or Part No. : Pure Matte Tin. Test Item : Cd,Pb,Hg,CrVI.

Tests Conducted:

As Requested By The Applicant, For Details Refer To Attached Pages

Prepared And Checked By:

For Intertek Testing Services Wuxi Ltd.

Jessica Lu General Manager

Page 1 Of 4

Intertek Testing Services Wuxi Ltd.



Annex 4: Analysis Result of Matte-Tin plating (page 2 of 4)



TEST REPORT Number: WUXH00005709

Tests Conducted (As Requested By The Applicant)

1 RoHS Directives Test

(A) Test Result Summary:

| Testing Item | Result | |
|----------------------------------------------------------------------------------------------------------------|--------|--|
| resulig Item | (1) | |
| Cadmium (Cd) Content (mg/kg)/Plating | ND | |
| Lead (Pb) Content (mg/kg)/Plating | 29 | |
| Mercury (Hg) Content (mg/kg)/Plating | ND | |
| Chromium (VI)(Cr ⁶⁺) Result (By Boiling Water Extraction On Metal) (mg/kg With 50cm ²) | N | |

Remark

mg/kg = Milligram Per Kilogram = ppm

mg/kg With 50cm² = Milligram Per Kilogram With 50 Square Centimeter

ND = Not Detected

N=Negative

Tested Component:

(1) Metal Pin Plating.

(B)RoHS Requirement:

| (b)None Requirement | | |
|-----------------------------------|-------------------|--|
| Restricted Substances | Limits | |
| Cadmium (Cd) | 0.01% (100 mg/kg) | |
| Lead (Pb) | 0.1% (1000 mg/kg) | |
| Mercury (Hg) | 0.1% (1000 mg/kg) | |
| Chromium (VI) (Cr ⁶⁺) | 0.1% (1000 ma/ka) | |

The Above Limits Were Quoted From 2002/95/EC And Amendment 2005/618/EC For Homogeneous Material.

(C) Test Method:

| <u>Testing Item</u> | <u>Testing Method</u> | Reporting Limit |
|----------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------|
| Cadmium (Cd)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Lead (Pb)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Mercury (Hg)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Chromium (VI) (Cr ⁶⁺) Content (For Metal) | With Reference To IEC 62321 Edition 1.0: 2008, By Boiling Water Extraction And Determined By UV-VIS Spectrophotometer | 0.02mg/kg With 50cm² (In Testing Solution) |

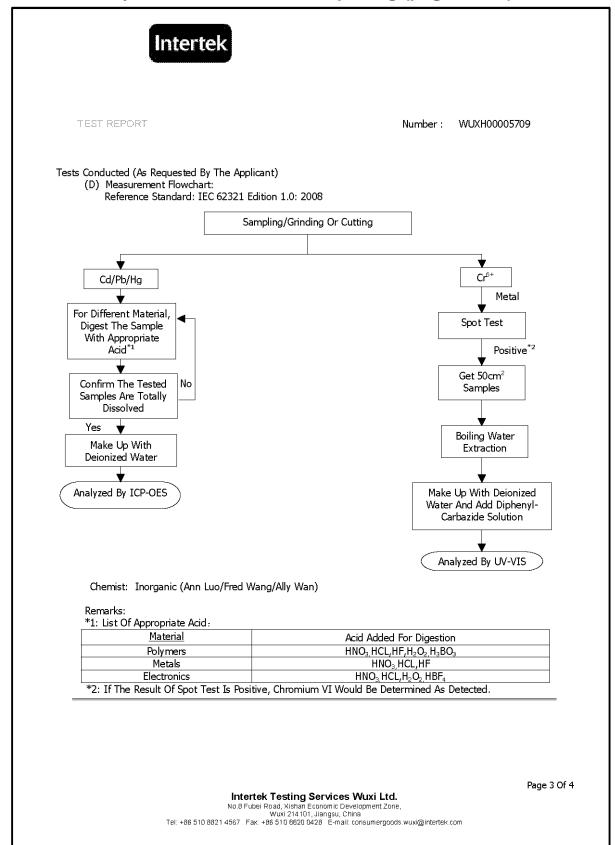
Date Sample Received: Aug 01, 2011 Testing Period: Aug 01, 2011 To Aug 04, 2011

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Intertek Testing Services Wuxi Ltd.



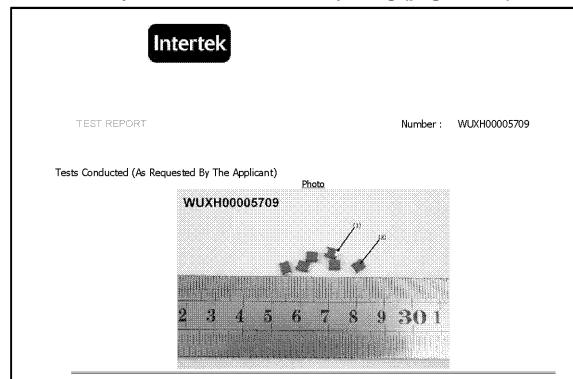
Annex 4: Analysis Result of Matte-Tin plating (page 3 of 4)



August 13, 2011 Littelfuse, Inc. Annex 4-3



Annex 4: Analysis Result of Matte-Tin plating (page 4 of 4)



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Intertek Testing Services Wuxi Ltd.



Annex 5: Analysis Result of Ni-plated Wafer (Page 1 of 5)



TEST REPORT Number: WUXH00005703

Applicant: CONCORD SEMICONDUCTOR(WUXI) CO., LTD. Date: Aug 04, 2011

EAST 1#,ZHENFA 6 ROAD, SHUO FÁNG INDUSTRIAL PARK WUXI NATIONAL HIGH-TECH DEVELOPMENT ZONE, WUXI,JIANGSU,CHINA

Attn: ZHANG XIAOPENG

Sample Description As Declared:

One (1) Piece Of Submitted Sample Said To Be: **Silvery Grey Metal.**Item Name : Silicon Wafer With Nickel Plating.

Vendor : Concord. Component Or Part No. : Silicon+Nickel.

 $\label{eq:cd_pb_hdg_crVI_PBBs_PBDEs} Test\ Item \qquad : \ \mathsf{Cd}, \mathsf{Pb}, \mathsf{Hg}, \mathsf{CrVI}, \mathsf{PBBs}, \mathsf{PBDEs}.$

Remark : As Requested By The Applicant, Tested As A Whole And Sampled Randomly.

Tests Conducted:

As Requested By The Applicant, For Details Refer To Attached Pages

Prepared And Checked By:

For Intertek Testing Services Wuxi Ltd.

Jessica Lu General Manager

Page 1 Of 5

Intertek Testing Services Wuxi Ltd.



Annex 5: Analysis Result of Ni-plated Wafer (Page 2 of 5)



TEST REPORT Number: WUXH00005703

Tests Conducted (As Requested By The Applicant)

1 RoHS Directives Test

(A) Test Result Summary:

| Testing Item | Result |
|------------------------------------------------------------------|--------|
| Cadmium (Cd) Content (mg/kg) | ND |
| Lead (Pb) Content (mg/kg) | 48 |
| Mercury (Hg) Content (mg/kg) | ND |
| Chromium (VI) (Cr ⁶⁺) Content (mg/kg)(For Non-Metal) | ND |
| Polybrominated Biphenyls (PBBs)(mg/kg) | |
| Monobrominated Biphenyls (MonoBB) | ND |
| Dibrominated Biphenyls (DiBB) | ND |
| Tribrominated Biphenyls (TriBB) | ND |
| Tetrabrominated Biphenyls (TetraBB) | ND |
| Pentabrominated Biphenyls (PentaBB) | ND |
| Hexabrominated Biphenyls (HexaBB) | ND |
| Heptabrominated Biphenyls (HeptaBB) | ND |
| Octabrominated Biphenyls (OctaBB) | ND |
| Nonabrominated Biphenyls (NonaBB) | ND |
| Decabrominated Biphenyl (DecaBB) | ND |
| Polybrominated Diphenyl Ethers (PBDEs)(mg/kg) | |
| Monobrominated Diphenyl Ethers (MonoBDE) | ND |
| Dibrominated Diphenyl Ethers (DiBDE) | ND |
| Tribrominated Diphenyl Ethers (TriBDE) | ND |
| Tetrabrominated Diphenyl Ethers (TetraBDE) | ND |
| Pentabrominated Diphenyl Ethers (PentaBDE) | ND |
| Hexabrominated Diphenyl Ethers (HexaBDE) | ND |
| Heptabrominated Diphenyl Ethers (HeptaBDE) | ND |
| Octabrominated Diphenyl Ethers (OctaBDE) | ND |
| Nonabrominated Diphenyl Ethers (NonaBDE) | ND |
| Decabrominated Diphenyl Ether (DecaBDE) | ND |

Remark:

mg/kg = Milligram Per Kilogram = ppm

ND = Not Detected

Page 2 Of 5

Intertek Testing Services Wuxi Ltd.



Annex 5: Analysis Result of Ni-plated Wafer (Page 3 of 5)



TEST REPORT Number: WUXH00005703

Tests Conducted (As Requested By The Applicant)

(B)RoHS Requirement:

| (b)Norio requirement. | |
|----------------------------------------|-------------------|
| Restricted Substances | Limits |
| Cadmium (Cd) | 0.01% (100 mg/kg) |
| Lead (Pb) | 0.1% (1000 mg/kg) |
| Mercury (Hg) | 0.1% (1000 mg/kg) |
| Chromium (VI) (Cr ⁶⁺) | 0.1% (1000 mg/kg) |
| Polybrominated Biphenyls (PBBs) | 0.1% (1000 mg/kg) |
| Polybrominated Diphenyl Ethers (PBDEs) | 0.1% (1000 mg/kg) |

The Above Limits Were Quoted From 2002/95/EC And Amendment 2005/618/EC For Homogeneous Material.

(C) Test Method:

| Testing Item | Testing Method | Reporting Limit |
|-------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------|
| Cadmium (Cd)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Lead (Pb)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Mercury (Hg)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Chromium (VI) (Cr ⁶⁺) Content (For Non-Metal) | With Reference To IEC 62321 Edition 1.0: 2008, By Alkaline Digestion And Determined By UV-VIS Spectrophotometer | 1 mg/kg |
| Polybrominated Biphenyls (PBBs)& Polybrominated Diphenyl Ethers (PBDEs) | With Reference To IEC IEC 62321 Edition 1.0: 2008, By Solvent Extraction And Determined By GC/MS And Further HPLC Confirmation When Necessary. | 5 mg/kg |

Date Sample Received: Aug 01, 2011

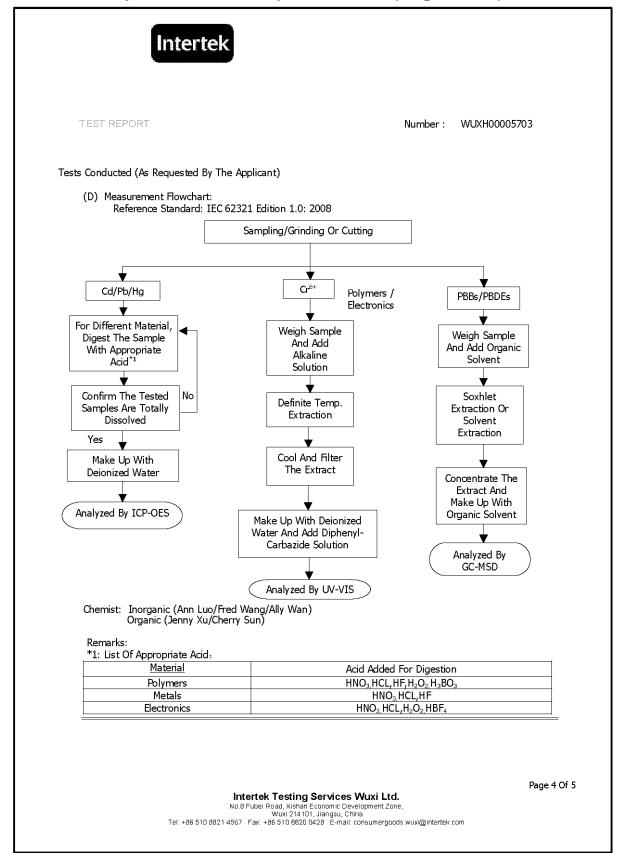
Testing Period: Aug 01, 2011 To Aug 04, 2011

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Intertek Testing Services Wuxi Ltd.

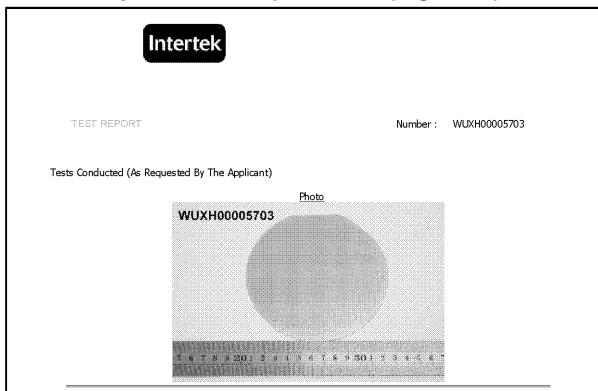


Annex 5: Analysis Result of Ni-plated Wafer (Page 4 of 5)





Annex 5: Analysis Result of Ni-plated Wafer (Page 5 of 5)



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Intertek Testing Services Wuxi Ltd.



Annex 6: Analysis Result of Passivation Glass (Page 1 of 7)



TEST REPORT Number: WUXH00005704

Date:

Aug 05, 2011

Applicant: CONCORD SEMICONDUCTOR(WUXI) CO., LTD.

EAST 1#,ZHENFA 6 ROAD, SHUO FÁNG INDUSTRIAL PARK WUXI NATIONAL HIGH-TECH DEVELOPMENT ZONE, WUXI, JIANGSU, CHINA

Attn: ZHANG XIAOPENG

Sample Description As Declared:

One (1) Piece Of Submitted Sample Said To Be: White Power. : Wafer Passiwation. Item Name

Vendor : Propriety. Component Or Part No. : Propriety.

: Cd,Pb,Hg,CrVI,PBBs,PBDEs,F,Cl,Br,I. Test Item

Tests Conducted:

As Requested By The Applicant, For Details Refer To Attached Pages

Prepared And Checked By:

For Intertek Testing Services Wuxi Ltd.

Jessica Lu

General Manager

Page 1 Of 7

Intertek Testing Services Wuxi Ltd.



Annex 6: Analysis Result of Passivation Glass (Page 2 of 7)



TEST REPORT Number: WUXH00005704

Tests Conducted (As Requested By The Applicant)

1 RoHS Directives Test

(A) Test Result Summary:

| (A) Test Result Summary: Testing Item | Result |
|------------------------------------------------------------------|--------|
| Cadmium (Cd) Content (mg/kg) | ND ND |
| Lead (Pb) Content (mg/kg) | 185100 |
| Mercury (Hg) Content (mg/kg) | ND |
| Chromium (VI) (Cr ⁶⁺) Content (mg/kg)(For Non-Metal) | ND |
| Polybrominated Biphenyls (PBBs)(mg/kg) | |
| Monobrominated Biphenyls (MonoBB) | ND |
| Dibrominated Biphenyls (DiBB) | ND |
| Tribrominated Biphenyls (TriBB) | ND |
| Tetrabrominated Biphenyls (TetraBB) | ND |
| Pentabrominated Biphenyls (PentaBB) | ND |
| Hexabrominated Biphenyls (HexaBB) | ND |
| Heptabrominated Biphenyls (HeptaBB) | ND |
| Octabrominated Biphenyls (OctaBB) | ND |
| Nonabrominated Biphenyls (NonaBB) | ND |
| Decabrominated Biphenyl (DecaBB) | ND |
| Polybrominated Diphenyl Ethers (PBDEs)(mg/kg) | |
| Monobrominated Diphenyl Ethers (MonoBDE) | ND |
| Dibrominated Diphenyl Ethers (DiBDE) | ND |
| Tribrominated Diphenyl Ethers (TriBDE) | ND |
| Tetrabrominated Diphenyl Ethers (TetraBDE) | ND |
| Pentabrominated Diphenyl Ethers (PentaBDE) | ND |
| Hexabrominated Diphenyl Ethers (HexaBDE) | ND |
| Heptabrominated Diphenyl Ethers (HeptaBDE) | ND |
| Octabrominated Diphenyl Ethers (OctaBDE) | ND |
| Nonabrominated Diphenyl Ethers (NonaBDE) | ND |
| Decabrominated Diphenyl Ether (DecaBDE) | ND |

Remark:

mg/kg = Milligram Per Kilogram = ppm

ND = Not Detected

#=The Result Is For Reference Only.

Page 2 Of 7

Intertek Testing Services Wuxi Ltd.



Annex 6: Analysis Result of Passivation Glass (Page 3 of 7)



TEST REPORT Number: WUXH00005707

Tests Conducted (As Requested By The Applicant)

(B)RoHS Requirement:

| (b)Norio requirement. | |
|----------------------------------------|-------------------|
| Restricted Substances | Limits |
| Cadmium (Cd) | 0.01% (100 mg/kg) |
| Lead (Pb) | 0.1% (1000 mg/kg) |
| Mercury (Hg) | 0.1% (1000 mg/kg) |
| Chromium (VI) (Cr ⁶⁺) | 0.1% (1000 mg/kg) |
| Polybrominated Biphenyls (PBBs) | 0.1% (1000 mg/kg) |
| Polybrominated Diphenyl Ethers (PBDEs) | 0.1% (1000 mg/kg) |

The Above Limits Were Quoted From 2002/95/EC And Amendment 2005/618/EC For Homogeneous Material.

(C) Test Method:

| Testing Item | Testing Method | Reporting Limit |
|-------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------|
| Cadmium (Cd)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Lead (Pb)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Mercury (Hg)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Chromium (VI) (Cr ⁶⁺) Content (For Non-Metal) | With Reference To IEC 62321 Edition 1.0: 2008, By Alkaline Digestion And Determined By UV-VIS Spectrophotometer | 1 mg/kg |
| Polybrominated Biphenyls (PBBs)& Polybrominated Diphenyl Ethers (PBDEs) | With Reference To IEC IEC 62321 Edition 1.0: 2008, By Solvent Extraction And Determined By GC/MS And Further HPLC Confirmation When Necessary. | 5 mg/kg |

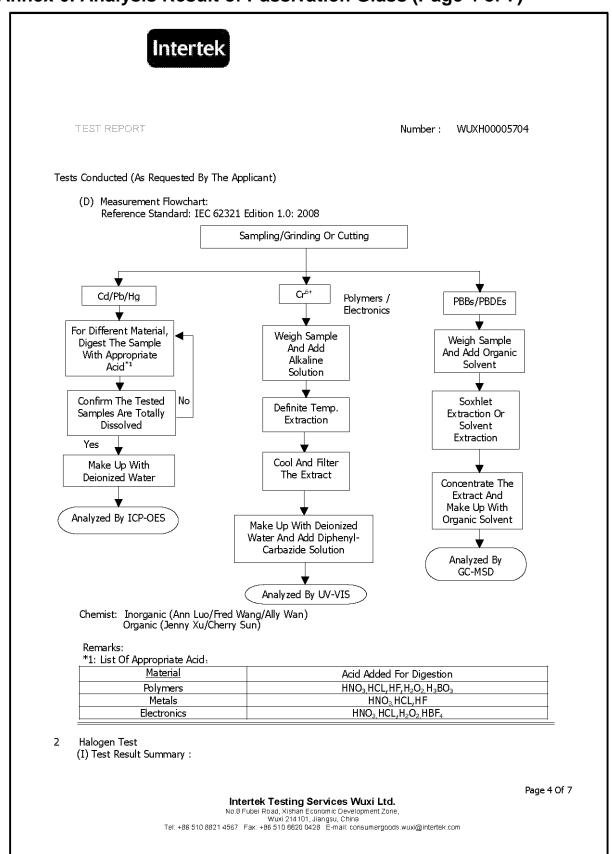
Date Sample Received: Aug 01, 2011 Testing Period: Aug 01, 2011 To Aug 04, 2011

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Intertek Testing Services Wuxi Ltd.



Annex 6: Analysis Result of Passivation Glass (Page 4 of 7)



August 13, 2011 Littelfuse, Inc. Annex 6-4



Annex 6: Analysis Result of Passivation Glass (Page 5 of 7)



TEST REPORT Number: WUXH00005704

Tests Conducted (As Requested By The Applicant)

Halogen Content:

| Testing Item | Result (ppm) |
|----------------------|--------------|
| Fluorine (F) Content | ND |
| Chlorine (CI)Content | ND |
| Bromine (Br) Content | ND |
| Iodine (I) Content | ND |

Remarks: ppm = Parts Per Million = mg/kg

ND = Not Detected

Date Sample Received: Aug 01, 2011

Testing Period: Aug 01, 2011 To Aug 05, 2011

(II) Test Method:

| (11) restriction : | | |
|--------------------------------|-----------------------------------------------------------------------------------------------------------|-----------------|
| Testing Item | Testing Method | Reporting Limit |
| Halogen (F, Cl, Br, I) Content | With Reference To EN 14582:2007 By Combustion In A Calorimetric Bomb And Determined By Ion Chromatography | 50 ppm |
| | | |

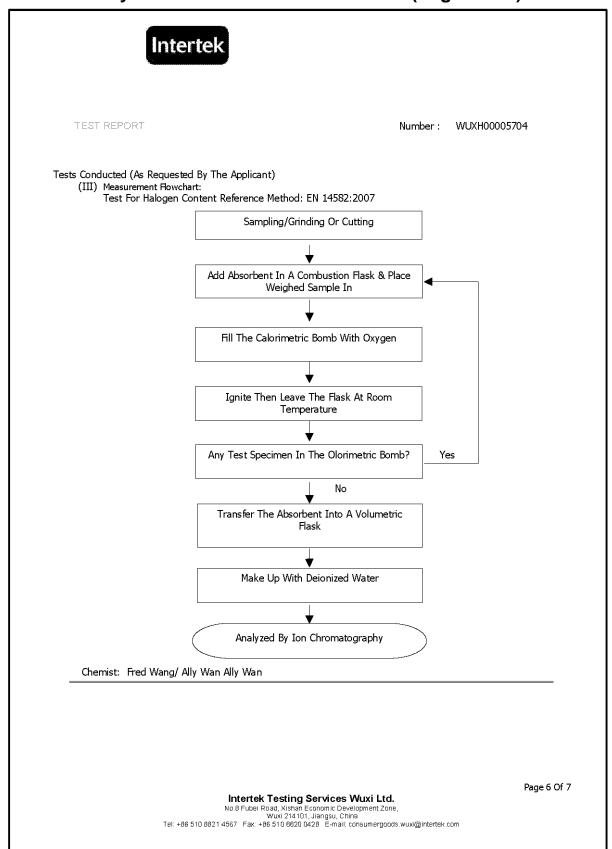
Remarks: Reporting Limit = Quantitation Limit Of Analyte In Sample

Page 5 Of 7

Intertek Testing Services Wuxi Ltd.



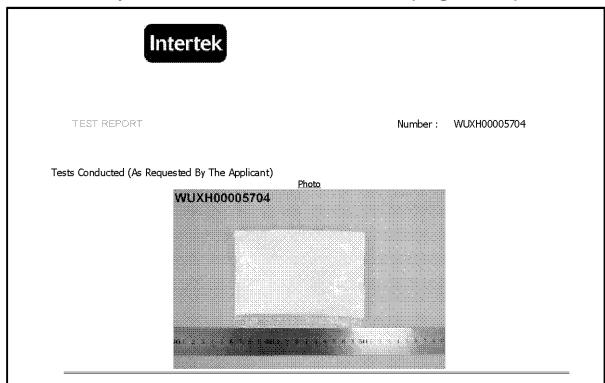
Annex 6: Analysis Result of Passivation Glass (Page 6 of 7)



August 13, 2011 Littelfuse, Inc. Annex 6-6



Annex 6: Analysis Result of Passivation Glass (Page 7 of 7)



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Intertek Testing Services Wuxi Ltd.



Annex 7: Analysis Result of Die Bonding Solder (Page 1 of 8)



TEST REPORT Number: WUXH00005720S1

Date:

AUG 05, 2011

Aug 12, 2011

THIS IS TO SUPERSEDE REPORT NO. WUXH00005720 DATED

Applicant: CONCORD SEMICONDUCTOR(WUXI) CO., LTD.

EAST 1#,ZHENFA 6 ROAD, SHUO FANG
INDUSTRIAL PARK WUXI NATIONAL HIGH-TECH
DEVELOPMENT ZONE, WUXI,JIANGSU,CHINA

Attn: ZHANG XIAOPENG

Sample Description As Declared:

One (1) Piece Of Submitted Sample Said To Be: Gray Paste.

Item Name : Solder Paste.

Vendor : Heraeus Materials Technology Shanghai Ltd.

Component Or Part No. : F367SN10-90Pb.

Test Item : Cd,Pb,Hg,CrVI,PBBs,PBDEs,F,Cl,Br,I.

Tests Conducted:

As Requested By The Applicant, For Details Refer To Attached Pages

Prepared And Checked By: For Intertek Testing Services Wuxi Ltd.

Jessica Lu General Manager

Page 1 Of 7

Intertek Testing Services Wuxi Ltd.



Annex 7: Analysis Result of Die Bonding Solder (Page 2 of 8)



TEST REPORT Number: WUXH00005720S1

Tests Conducted (As Requested By The Applicant)

1 RoHS Directives Test

(A) Test Result Summary

| (A) Test Result Summary: | |
|------------------------------------------------------------------|--------|
| Testing Item | Result |
| Cadmium (Cd) Content (mg/kg) | ND |
| Lead (Pb) Content (mg/kg) | 912000 |
| Mercury (Hg) Content (mg/kg) | ND |
| Chromium (VI) (Cr ⁶⁺) Content (mg/kg)(For Non-Metal) | ND |
| Polybrominated Biphenyls (PBBs)(mg/kg) | |
| Monobrominated Biphenyls (MonoBB) | ND |
| Dibrominated Biphenyls (DiBB) | ND |
| Tribrominated Biphenyls (TriBB) | ND |
| Tetrabrominated Biphenyls (TetraBB) | ND |
| Pentabrominated Biphenyls (PentaBB) | ND |
| Hexabrominated Biphenyls (HexaBB) | ND |
| Heptabrominated Biphenyls (HeptaBB) | ND |
| Octabrominated Biphenyls (OctaBB) | ND |
| Nonabrominated Biphenyls (NonaBB) | ND |
| Decabrominated Biphenyl (DecaBB) | ND |
| Polybrominated Diphenyl Ethers (PBDEs)(mg/kg) | |
| Monobrominated Diphenyl Ethers (MonoBDE) | ND |
| Dibrominated Diphenyl Ethers (DiBDE) | ND |
| Tribrominated Diphenyl Ethers (TriBDE) | ND |
| Tetrabrominated Diphenyl Ethers (TetraBDE) | ND |
| Pentabrominated Diphenyl Ethers (PentaBDE) | ND |
| Hexabrominated Diphenyl Ethers (HexaBDE) | ND |
| Heptabrominated Diphenyl Ethers (HeptaBDE) | ND |
| Octabrominated Diphenyl Ethers (OctaBDE) | ND |
| Nonabrominated Diphenyl Ethers (NonaBDE) | ND |
| Decabrominated Diphenyl Ether (DecaBDE) | ND |

Remark:

mg/kg = Milligram Per Kilogram = ppm

ND = Not Detected

= The Result Is For Reference Only.

Page 2 Of 7

Intertek Testing Services Wuxi Ltd.



Annex 7: Analysis Result of Die Bonding Solder (Page 3 of 8)



TEST REPORT Number: WUXH00005720S1

Tests Conducted (As Requested By The Applicant)

(B)RoHS Requirement:

| (b)Nons requirement. | |
|----------------------------------------|-------------------|
| Restricted Substances | Limits |
| Cadmium (Cd) | 0.01% (100 mg/kg) |
| Lead (Pb) | 0.1% (1000 mg/kg) |
| Mercury (Hg) | 0.1% (1000 mg/kg) |
| Chromium (VI) (Cr ⁶⁺) | 0.1% (1000 mg/kg) |
| Polybrominated Biphenyls (PBBs) | 0.1% (1000 mg/kg) |
| Polybrominated Diphenyl Ethers (PBDEs) | 0.1% (1000 mg/kg) |

The Above Limits Were Quoted From 2002/95/EC And Amendment 2005/618/EC For Homogeneous Material.

(C) Test Method:

| <u>Testing Item</u> | <u>Testing Method</u> | Reporting Limit |
|-------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------|-----------------|
| Cadmium (Cd)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Lead (Pb)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Mercury (Hg)Content | With Reference To IEC 62321 Edition 1.0: 2008, By Acid Digestion And Determined By ICP-OES | 2 mg/kg |
| Chromium (VI) (Cr ⁵⁺) Content (For Non-Metal) | With Reference To IEC 62321 Edition 1.0: 2008, By Alkaline Digestion And Determined By UV-VIS Spectrophotometer | 1 mg/kg |
| Polybrominated Biphenyls (PBBs)& Polybrominated Diphenyl Ethers (PBDEs) | With Reference To IEC 62321 Edition 1.0: 2008, By Solvent Extraction And Determined By GC-MSD And Further HPLC Confirmation When Necessary. | 5 mg/kg |

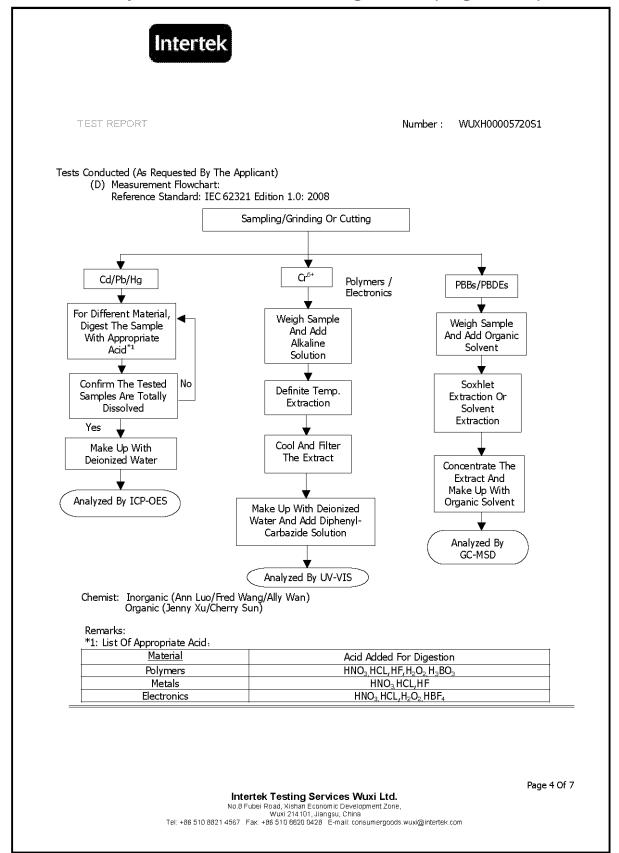
Date Sample Received: Aug 01, 2011 Testing Period: Aug 01, 2011 To Aug 05, 2011

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Intertek Testing Services Wuxi Ltd.



Annex 7: Analysis Result of Die Bonding Solder (Page 4 of 8)



August 13, 2011 Littelfuse, Inc. Annex 7-4



Annex 7: Analysis Result of Die Bonding Solder (Page 5 of 8)



TEST REPORT Number: WUXH00005720S1

Tests Conducted (As Requested By The Applicant)

2 Halogen Test

(I) Test Result Summary :

Halogen Content:

| Testing Item | Result (ppm) |
|----------------------|--------------|
| Fluorine (F) Content | ND |
| Chlorine (CI)Content | ND |
| Bromine (Br) Content | ND |
| Iodine (I) Content | ND |

Remarks: ppm = Parts Per Million = mg/kg

ND = Not Detected

Date Sample Received: Aug 01, 2011

Testing Period: Aug 01, 2011 To Aug 05, 2011

(II) Test Method:

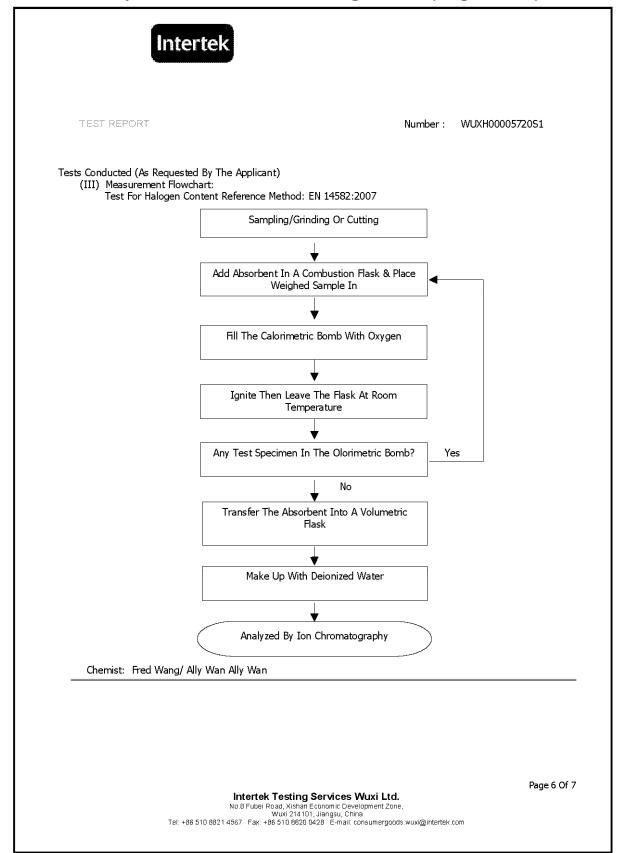
| Testing Item | Testing Method | Reporting Limit |
|----------------------------------|-----------------------------------------------------------------------------------------------------------|--------------------|
| | With Reference EN 14582:2007 By Combustion In A Calorimetric Bomb And Determined By Ion Chromatography | 50 ppm |
| Remarks: Reporting Limit = Quant | itation Limit Of Analyte In Sample | , |

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Intertek Testing Services Wuxi Ltd.



Annex 7: Analysis Result of Die Bonding Solder (Page 6 of 8)





Annex 7: Analysis Result of Die Bonding Solder (Page 7 of 8)



TEST REPORT Number: WUXH00005720S1

Tests Conducted (As Requested By The Applicant)



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Intertek Testing Services Wuxi Ltd.



Annex 7: Analysis Result of Die Bonding Solder (Page 8 of 8)



To: CONCORD SEMICONDUCTOR(WUXI) CO., LTD.

Attention: ZHANG XIAOPENG Date: Aug 12, 2011

Re : Report Revision Notification

Labtest Report Number WUXH00005720 date Aug 05, 2011

Please be informed that all the content recorded in the above captioned report will be void. This captioned report is now superseded by a revised Labtest Report, Number WUXH00005720S1 , issued on Aug 12, 2011 .

Thank you for your attention

Prepared And Checked By: For Intertek Testing Services Wuxi Ltd.

Jessica Lu General Manager

Intertek Testing Services Wuxi Ltd.
No.3 Fubel Pload, Xishan Economic Development Zone,
Vivud 214101, Jüngeu, China
無錫天祥實量技術服務有限公司
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Annex 8: Applicable RoHS exemptions (2011/65/EU Annex III)

| 1.7.2011 | Ŀ | Official Journal of the Europea | ın Union | L 174/103 |
|----------|----------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------|-----------|
| | | Excraption | Scope and dates of applicability | |
| | 6 (a) | Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight | | |
| | 6(b) | Lead as an alloying element in aluminium containing up to 0,4 % lead by weight | | |
| | б (c) | Copper alloy containing up to 4 % lead by weight | | |
| | 7 (a) | Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) | | |
| | 7(b) | Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission, and network management for tele- communications | | |
| | 7(c)-I | Flectrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound | | |
| | 7(c)-11 | Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher | | |
| | 7(c)-III | Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC | Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013 | |
| | 8(a) | Cadmium and its compounds in one shot pellet type thermal cut-offs | Expires on 1 January 2012 and after that date may be used in spare parts for FEE placed on the market before 1 January 2012 | |
| | 8 (b) | Cadmium and its compounds in electrical contacts | | |
| | 9 | Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0.75 % by weight in the cooling solution | | |
| | 9(b) | Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications | | |
| | i I (a) | Lead used in C-press compliant pin connector systems | May be used in spare parts for FEE placed on the market before 24 September 2010 | |
| | 1 I (b) | Lead used in other than C-press compliant pin connector systems | Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013 | |
| | 12 | Lead as a coating material for the thermal conduction module C-ring | May be used in spare parts for EEE placed on the market before 24 September 2010 | |
| | 1 3(a) | Lead in white glasses used for optical applications | | |
| | 13(h) | Cadmium and lead in filter glasses and glasses used for reflectance standards | | |
| | 14 | Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight | Expired on 1 January 2011 and after that date may be used in spare parts for IEE placed on the market before 1 January 2011 | |

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